Nidec Advance Technology Corporation

March 18, 2026

Nidec Advance Technology to Exhibit Products at SEMICON China 2026

Nidec Advance Technology Corporation ("Nidec Advance Technology" or the "Company") announced today that it will exhibit products at SEMICON China 2026, an event to be held at the Shanghai New International Expo Centre in Shanghai, China, from Wednesday, March 25 – Friday, March 27, 2026.

This upcoming exhibition is one of China's largest trade fairs, with more than 4,500 booths of 1,000-plus companies that cover all of the semiconductor industry's processes ranging from designing to manufacturing to packaging to equipment to materials.

At this event, visitors to Nidec Advance Technology's booth will be able to see the Company showcase optical surface inspection machines for semiconductor wafer inspection, probe cards, and the newly developed multilayer organic substrate, which the Company exhibit for the first time in China. This substrate, which boasts both significantly advanced wiring density and high-speed signal transmission, is drawing high interest from those who work in the increasingly miniaturizing semiconductor inspection process.

In addition, by exhibiting products jointly with Nidec Instruments Corporation (a Nidec Group company), Nidec Advance Technology will integrate its inspection technology with Nidec Instruments' advanced wafer transfer robots to offer globally state-of-the-art total inspection and transfer solutions for semiconductor manufacturing processes.

About SEMICON China 2026
- Period: Wednesday, March 25 – Friday, March 27, 2026
- Venue: Shanghai New International Expo Centre
- Nidec Advance Technology: E6713
- Official website: https://www.semiconchina.org/

Nidec Advance Technology's exhibits will include:
- RWi-300MK3 (3D/2D/SD wafer bump inspection instrument)
- AURCA series (3D/AFVI+AI inspection instrument for large substrates)
- AURCA-S series (2D + 3D inspection instrument for wafers and PLP)
- High-precision 2D/3D inspection solution for TGV
- Front-End/Back-End inspection solution for power semiconductor
- MLO substrate for probe card
- Probe card for semiconductor wafer inspection
- Semiconductor wafer transfer robot

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